2SB740

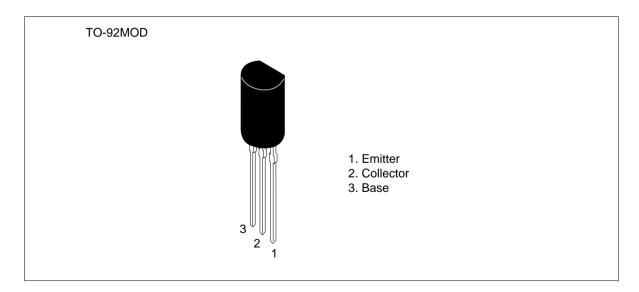
Silicon PNP Epitaxial

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Application

- Low frequency power amplifier
- Complementary pair with 2SD789

Outline





2SB740

Absolute Maximum Ratings (Ta = 25°C)

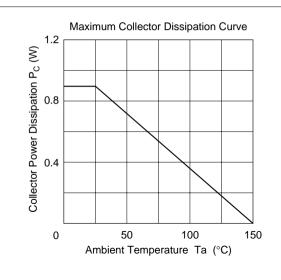
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-70	V
Collector to emitter voltage	V _{CEO}	-50	V
Emitter to base voltage	V_{EBO}	-6	V
Collector current	I _c	-1	A
Collector power dissipation	P _c	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

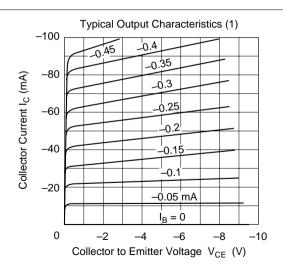
Electrical Characteristics (Ta = 25°C)

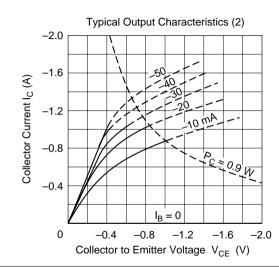
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-70	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\text{(BR)CEO}}$	-50	_	_	V	$I_{\text{C}} = -1 \text{ mA}, R_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{\text{(BR)EBO}}$	-6	_	_	V	$I_E = -10 \ \mu A, \ I_C = 0$
Collector cutoff current	I _{CBO}	_	_	-1	μΑ	$V_{CB} = -55 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-0.2	μΑ	$V_{EB} = -6 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	100	_	320		$V_{CE} = -2 \text{ V}, I_{C} = -0.1 \text{ A}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-0.6	V	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -0.1 \text{ A}$
Gain bandwidth product	f _T	_	150	_	MHz	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$
Collector output capacitance	Cob	_	35	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0,$ f = 1 MHz

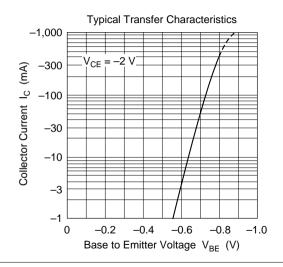
Note: 1. The 2SB740 is grouped by h_{FE} as follows.

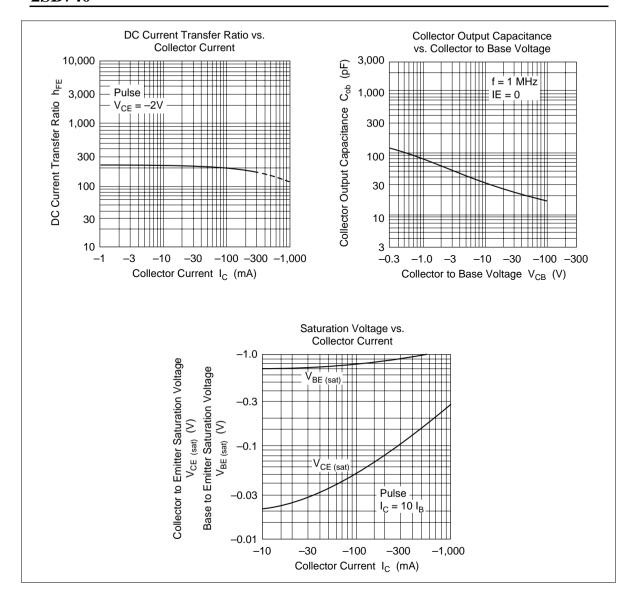
В	С
100 to 200	160 to 320



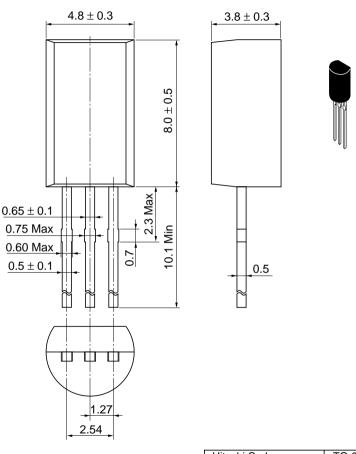








Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.35 g

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